

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC2373IUH-16#PBF

(Engineering Calculation)

QFN 5mm X 5mm Exp. Pad

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TOTAL MASS (g): 0.065241

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002549 | 1000000 | 39070.3632812 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.028382 | 975000 | 435031.375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000699 | 24000 | 10714.0771484 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000009 | 300 | 137.949493408 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000020 | 700 | 306.554443359 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.029110 | 1000000 | 446189.96875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001398 | 1000000 | 21432.3828125 | | |
| | | External Plating Total: | | | | 0.001398 | 1000000 | 21432.3828125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000635 | 1000000 | 9733.10351562 | | |
| | | Internal Plating Total: | | | | 0.000635 | 1000000 | 9733.10351562 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001068 | 750000 | 16370.0058594 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000356 | 250000 | 5456.66894531 | | |
| Die Attach Total: | | | | 0.001424 | 1000000 | 21826.6757812 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.003888 | 130000 | 59594.1796875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.025723 | 860000 | 394274.9375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |

| | | | | | | |
|----------------------------|----------------|-----------------------------|-----------|------------------------|----------------|----------------------|
| | | Carbon Black (C) | 1333-86-4 | 0.000299 | 10000 | 4582.98876953 |
| | | Encapsulation Total: | | 0.029910 | 1000000 | 458452.125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000215 | 1000000 | 3295.45996094 |
| | | | | TOTAL MASS (g): | | 0.065241 |